

N-Ch MOSFET

General Description

This WSR20N65F is produced using Truesemi's

advanced planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching

performance, and withstand high energy

pulse in the avalanche and commutation mode. These devices are well suited for

effighency switched mode power supplies, active power factor correction based on

half bridge topology.

Features

- High ruggedness
- · Fast switching
- 100% avalanche tested
- Improved dv/dt capability

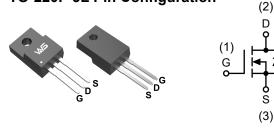
Product Summery

| BV _{DSS} | R _{DSON} | Ι _D |
|-------------------|-------------------|----------------|
| 650V | 400mΩ | 20A |

Applications

- Power Management .
- AC-DC Converter
- LED TV Back Light

TO-220F-3L Pin Configuration



Absolute Maximum Ratings T_c=25°C unless otherwise specified

| Symbol | Parameter | | Value | Units |
|-----------------------------------|--|-----------------------|-------------|-------|
| V _{DSS} | Drain-Source Voltage | | 650 | V |
| V_{GS} | Gate-Source Voltage | | ± 30 | V |
| | Drein Current | T _C = 25℃ | 20* | A |
| I _D | Drain Current | T _c = 100℃ | 12* | A |
| I _{DM} | Pulsed Drain Current | | 76* | A |
| E _{AS} | Single Pulsed Avalanche Energy | (Note 2) | 884 | mJ |
| E _{AR} | Repetitive Avalanche Energy | (Note 1) | 4 | mJ |
| I _{AR} | Repetitive avalanche current | (Note 1) | 20 | A |
| P _D | Power Dissipation (T _C = 25℃) | | 80 | W |
| T _J , T _{STG} | Operating and Storage Temperature | e Range | -55 to +150 | °C |

* Drain current limited by maximum junction temperature.

Thermal Resistance Characteristics

| Symbol Parameter | | Value | Units |
|------------------|---|-------|-------|
| R _{θJC} | Thermal Resistance, Junction-to-Case | 1.56 | °C/W |
| R _{eja} | Thermal Resistance, Junction-to-Ambient | 62.5 | °C/W |



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Electrical Characteristics T_c =25 °C unless otherwise specified

| Symbol | Parameter | Test Conditions | | Тур | Max | Units | |
|---------------------|--------------------------------------|--|---|-----|-----|-------|--|
| On Characteristics | | | | | | | |
| V_{GS} | Gate Threshold Voltage | V_{DS} = V_{GS} , I_{D} = 250 uA | 3 | | 5 | V | |
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} = 10 V, I _D = 10A | - | 400 | 480 | mΩ | |
| g _{fs} | Forward transfer conductance(note 3) | $V_{DS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$ (Note 3) | | 18 | | S | |

Off Characteristics

| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} = 0 V, I _D = 250 uA | 650 | | V |
|-------------------|------------------------------------|--|-----|----------|----|
| | Zara Cata Valtaga Drain Current | V _{DS} = 650 V, V _{GS} = 0 V | | 1 | |
| DSS | Zero Gate Voltage Drain Current | V _{DS} = 650 V, T _C =125°C | | 100 | uA |
| I _{GSSF} | Gate-Body Leakage Current, Forward | V _{GS} = 30 V, V _{DS} = 0 V | | 100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | V _{GS} =- 30 V, V _{DS} = 0 V | | -100 | nA |

Dynamic Characteristics

| C _{iss} | Input Capacitance | V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz | 5150 | pF |
|------------------|------------------------------|---|----------|--------|
| C _{oss} | Output Capacitance | | 264 | pF |
| C _{rss} | Reverse Transfer Capacitance | | 24 | pF |

Switching Characteristics

| t _{d(on)} | Turn-On Time | V _{DS} = 300 V, I _D = 20A, | | 149 | | ns |
|---------------------|---------------------|--|---|-----|----|----|
| t _r | Turn-On Rise Time | $R_{\rm G} = 25 \Omega$ | | 197 | - | ns |
| t _{d(off)} | Turn-Off Delay Time | (Note 3,4) | - | 83 | - | ns |
| t _f | Turn-Off Fall Time | | | 468 | - | ns |
| Qg | Total Gate Charge | V _{DS} = 480 V, I _D = 20A, | - | 57 | 65 | nC |
| Q _{gs} | Gate-Source Charge | V _{GS} = 10 V | | 23 | - | nC |
| Q _{gd} | Gate-Drain Charge | (Note 3,4) | | 13 | | nC |

Source-Drain Diode Maximum Ratings and Characteristics

| ۱ _s | Continuous Source-Drain Diode Forward Current | | | 20 | ٨ |
|-----------------|--|---|---------|-----|----|
| I _{SM} | Pulsed Source-Drain Diode Forward Current | | | 72 | A |
| V _{SD} | Source-Drain Diode Forward Voltage $I_{S} = 20A, V_{GS} = 0 V$ | | | 1.4 | V |
| t _{rr} | Reverse Recovery Time | I _S =20A, V _{GS} = 0 V | 435 | | ns |
| Q _{rr} | Reverse Recovery Charge | $di_{F}/dt = 100 \text{ A}/\mu \text{s}$ (Note 3,4) | 4.1 | | uC |

Note:

1. Repeated rating: Pulse width limited by safe operating area

2. L=5mH, IAS=20A, VDD=50V, RG=25 Ω , Starting TJ=25 $^{\circ}$ C

3. Pulse test: Pulse width≤300us, Duty cycle≤2%

4. Essentially independent of operating temperature typical characteristics



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Typical Characteristics

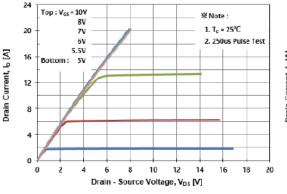


Fig. 1 Typical Output Characteristics

Fig. 2 Typical Output Characteristics

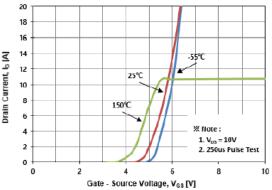


Fig.3 On-Resistance Variation with Drain Current and Gate Voltage

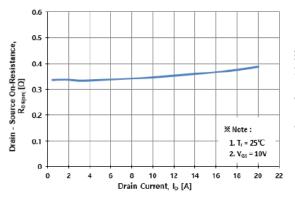


Fig. 5 Typical Capacitance Characteristics

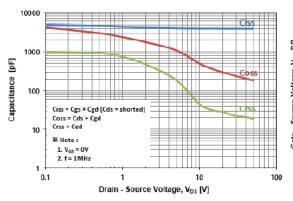


Fig. 4 Body Diode Forward Voltage Variation with Source Current

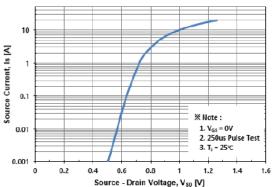
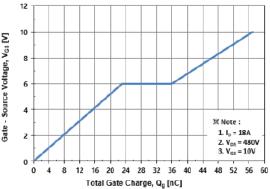


Fig. 6 Typical Total Gate Charge Characteristics





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Typical Characteristics

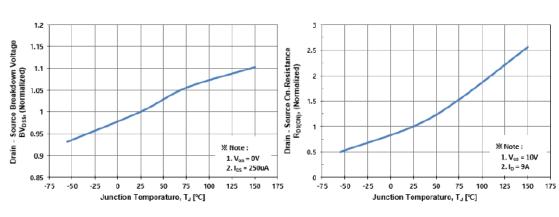
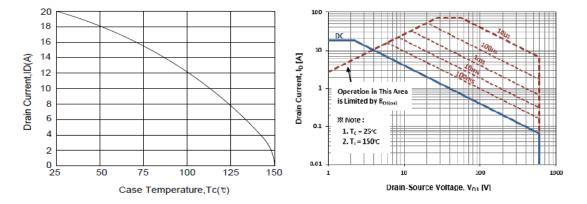


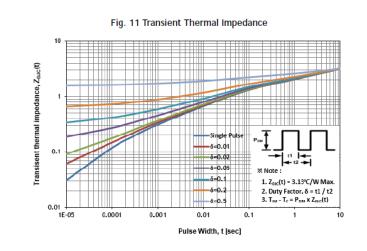
Fig. 7 Breakdown Voltage Variation vs. Temperature

Fig. 8 On-Resistance Variation vs. Temperature

Fig. 9 Maximum Drain Current vs. Case Temperature

Fig. 10 Maximum Safe Operating Area

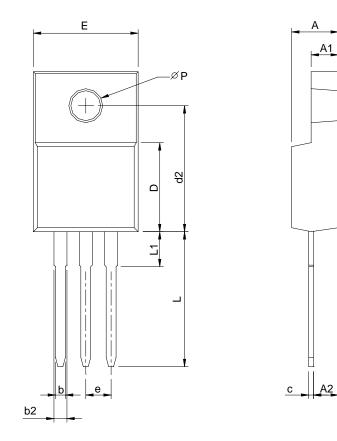


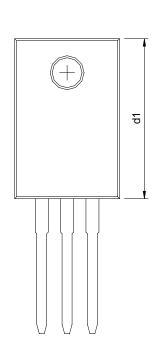




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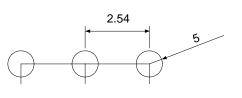
Packaging information





| S Y | TO-220F-3L | | | | |
|--------|------------|-------|--------|-------|--|
| SY MBO | MILLIM | ETERS | INCHES | | |
| O L | MIN. | MAX. | MIN. | MAX. | |
| Α | 4.20 | 4.80 | 0.165 | 0.189 | |
| A1 | 2.34 | 3.20 | 0.092 | 0.126 | |
| A2 | 2.10 | 2.90 | 0.083 | 0.114 | |
| b | 0.50 | 0.90 | 0.020 | 0.035 | |
| b2 | 0.91 | 1.90 | 0.035 | 0.075 | |
| С | 0.30 | 0.80 | 0.012 | 0.031 | |
| D | 8.10 | 9.40 | 0.319 | 0.370 | |
| d1 | 14.50 | 16.50 | 0.571 | 0.650 | |
| d2 | 12.10 | 12.90 | 0.476 | 0.508 | |
| Е | 9.70 | 10.70 | 0.382 | 0.421 | |
| е | 2.54 | BSC | 0.10 | 0 BSC | |
| L | 13.00 | 14.50 | 0.512 | 0.570 | |
| L1 | 1.60 | 4.00 | 0.063 | 0.157 | |
| Р | 3.00 | 3.60 | 0.118 | 0.142 | |

RECOMMENDED LAND PATTERN



81,7 PP



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